The background of the slide is a photograph of a large, ornate red brick building, likely the University of Liverpool, featuring a prominent clock tower with a spire and several other smaller spires. The sky is blue with some light clouds.

R&D of HV-CMOS detectors

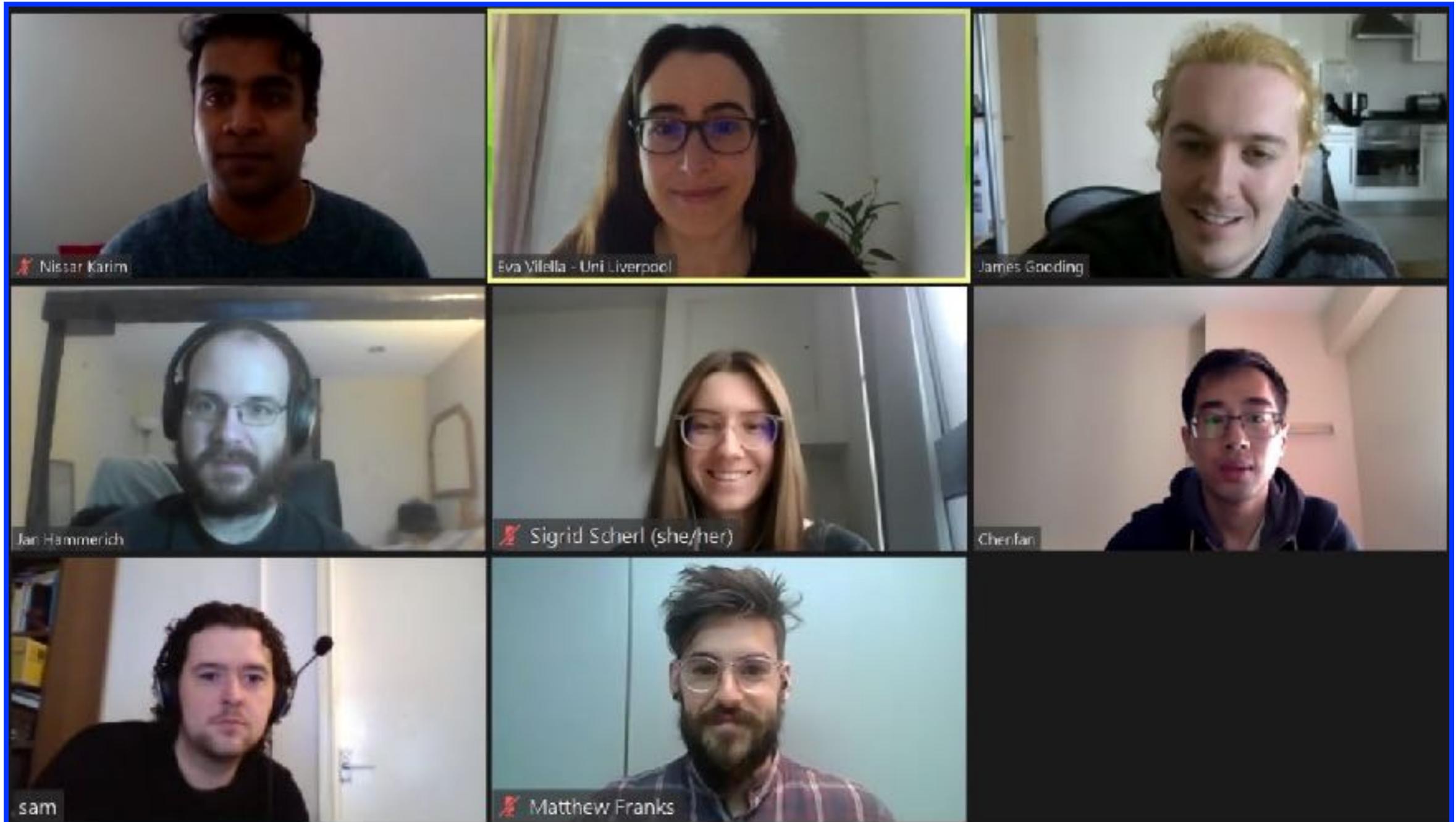
2020 HEP Annual Meeting Part II



UNIVERSITY OF
LIVERPOOL

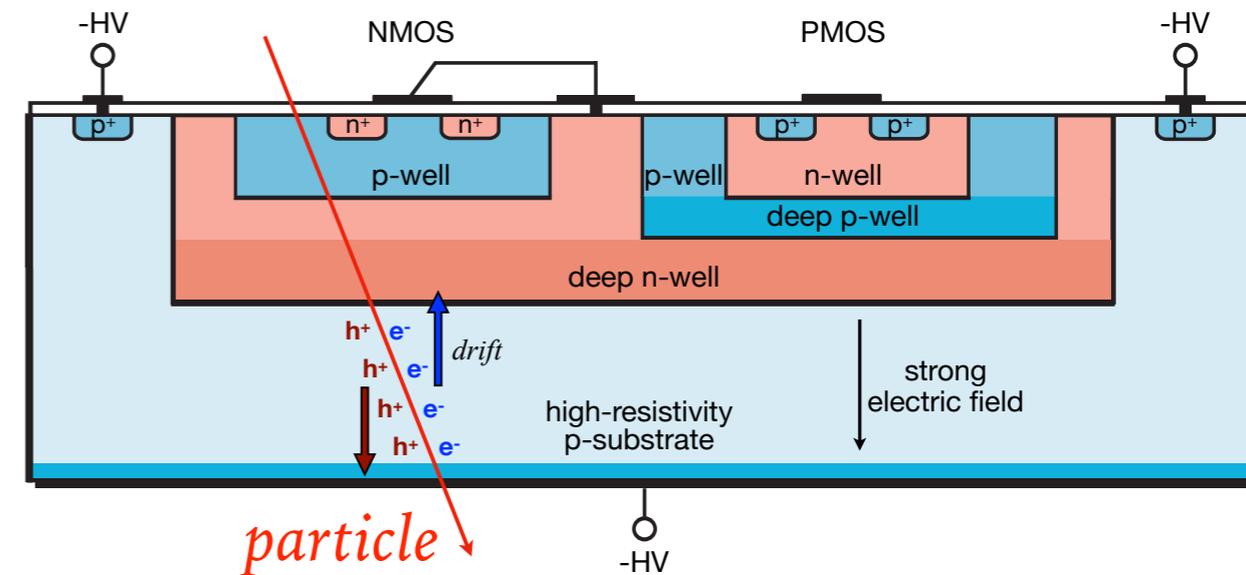
Chenfán Zhang
on behalf of the HV-CMOS group

- Who we are:



- What we do: Development of **HV-CMOS** pixel detectors for HEP experiments.

- Sensor and readout electronics are embedded in a single silicon wafer.
- Use commercial HV-CMOS processes.
- **Advantages:**
 - Single layer structure: low material thickness ($50\ \mu\text{m}$)
 - No bump-bonding: Small pixel size ($< 50\ \mu\text{m} \times 50\ \mu\text{m}$); reduced production cost ($\sim \text{£}100\text{k}/\text{m}^2$)
 - High bias voltage: fast charge collection by drift ($\sim 200\ \text{ps}$) and high radiation tolerance ($5 \times 10^{15}\ \text{1 MeV n}_{\text{eq}}/\text{cm}^2$)
- The Mu3e experiment has chosen HV-CMOS pixel detectors and many others are considering them: LHCb, proton EDM, PANDA. And applications fields other than HEP experiments.



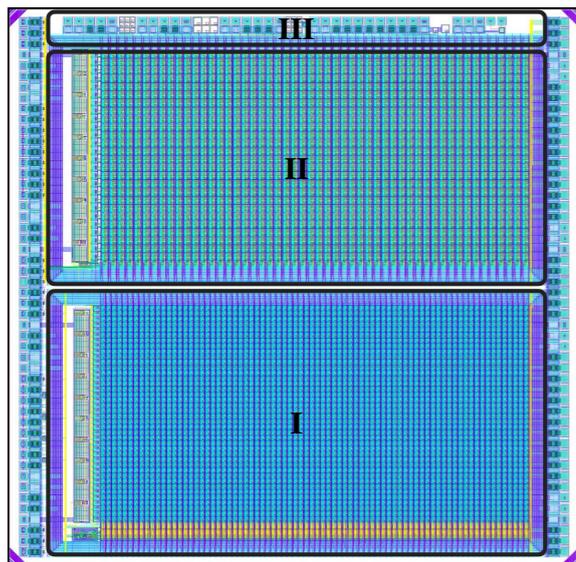
- **CERN-RD50** collaboration focuses on developing radiation-tolerant detectors.
- Liverpool has the leadership of its CMOS Working Group which does:
 - ASIC design
 - TCAD simulations
 - DAQ development
 - Chip performance evaluation
- Currently involves about 40 researchers from 14 institutes across Europe:



- Development goals:
 - High radiation tolerance (low leakage and high breakdown)
 - excellent time resolution and pixel granularity
- Recent prototypes designed by Liverpool in LFoundry 150 nm HV-CMOS process:

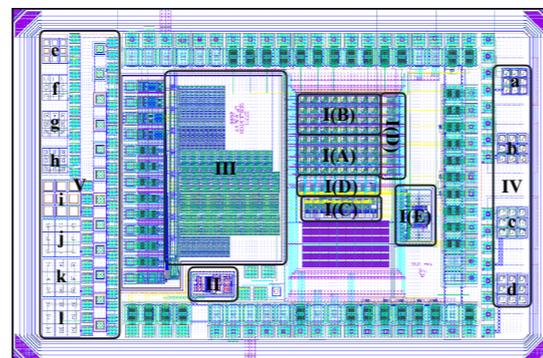
RD50-MPW1

received in Apr. 2018



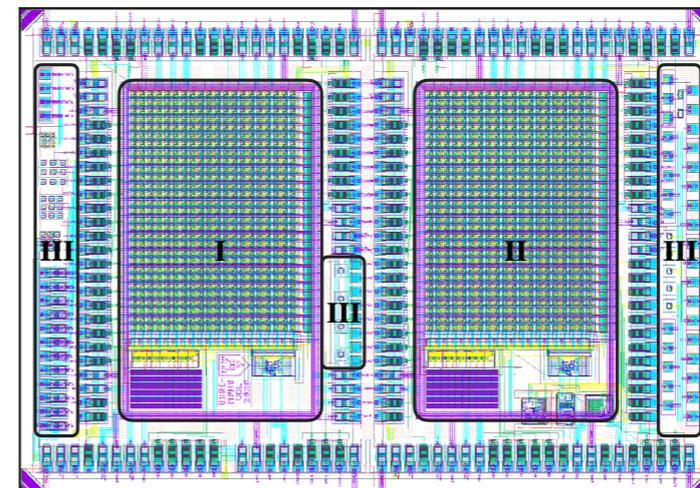
RD50-MPW2

received in Feb. 2020



UKRI-MPW0

submitted in Nov. 2020



RD50-MPW3

to be submitted
in Oct. 2021

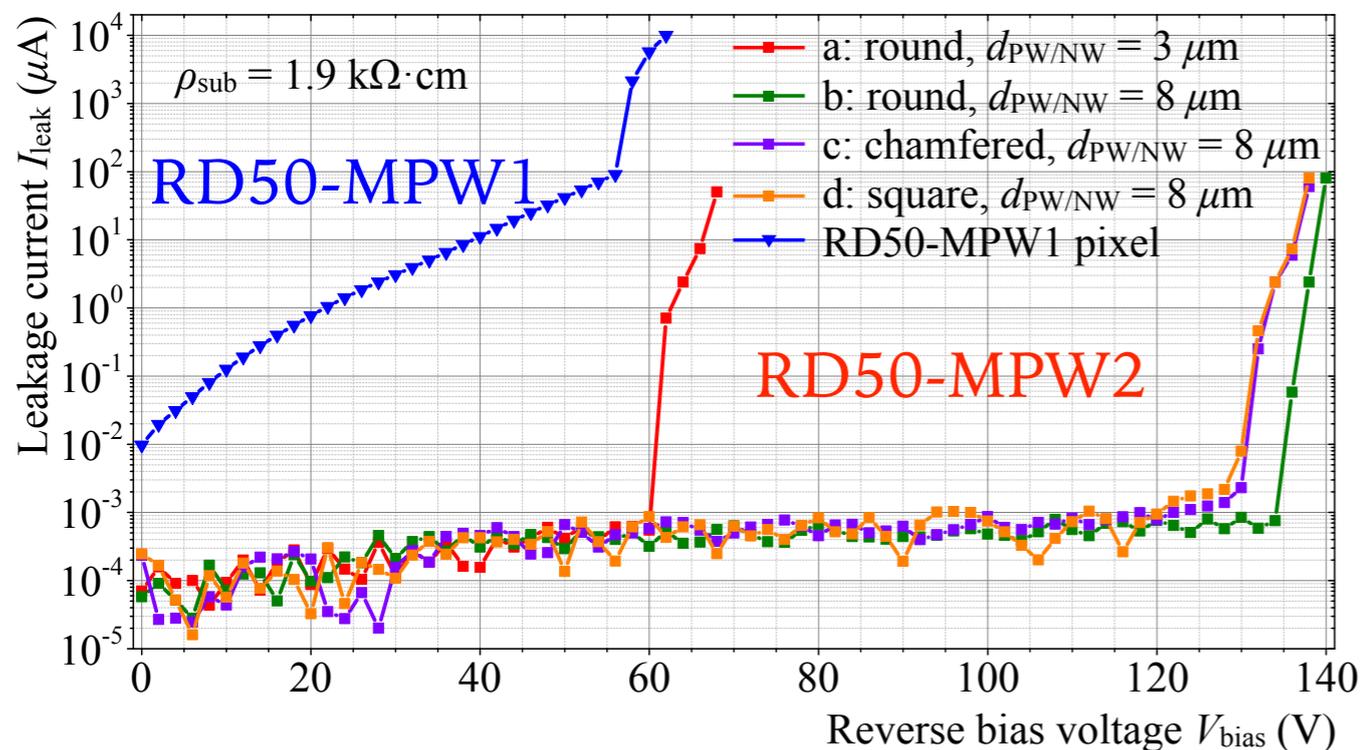
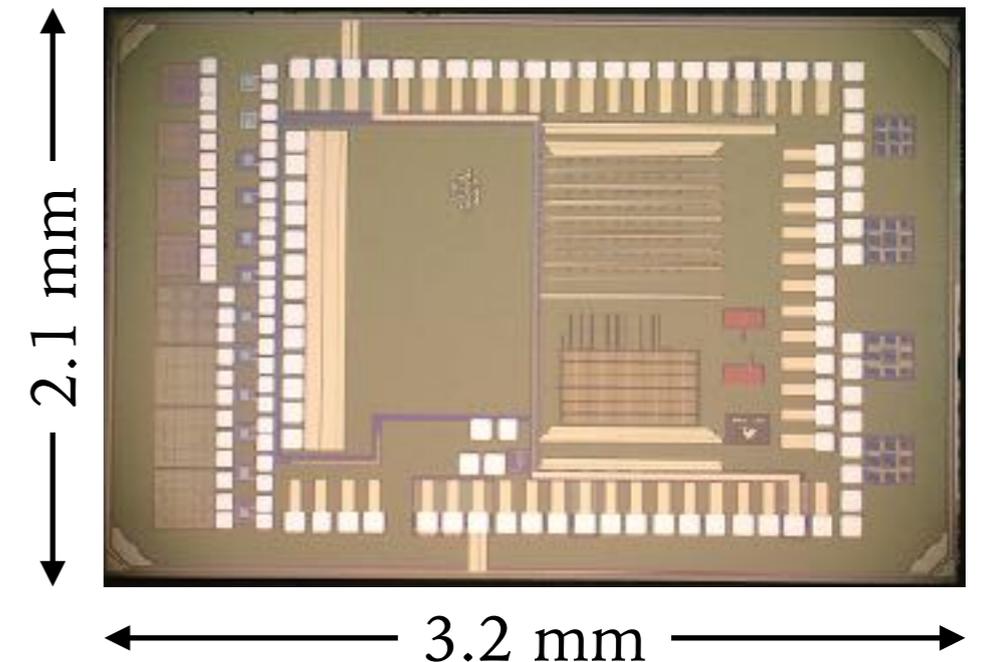


- **RD50-MPW1** - test the LF150 process; works well, but has high I_{Leak} and low V_{BD} .
- **RD50-MPW2** - fixes the issues in RD50-MPW1 and improves pixel performance.
- **UKRI-MPW0** - (Liverpool internal project) tests backside biasing.
- **RD50-MPW3** - implements large pixel matrices with advanced readout electronics.

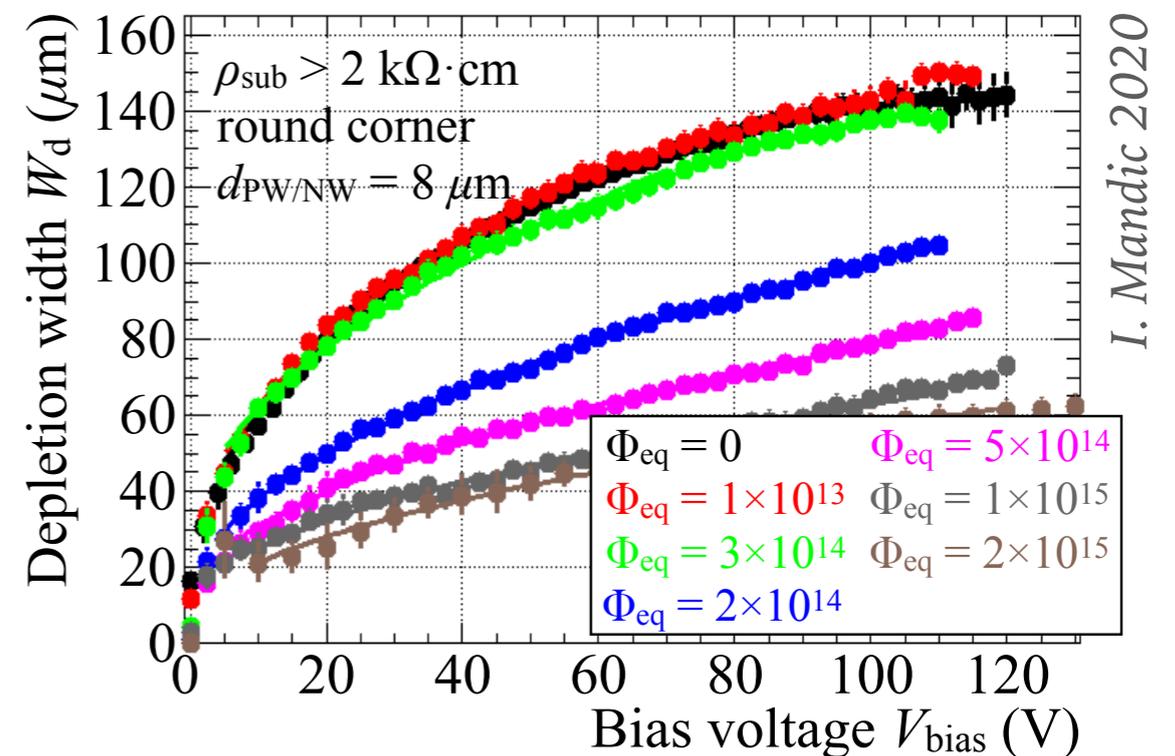
RD50-MPW2 Measured Results

- contains test structures and an 8×8 pixel matrix.
- Improvements:
 - Low leakage current
 - High breakdown voltage
 - Fast analog readout electronics
- Despite the difficulties caused by the pandemic, RD50-MPW2 has been well characterised in Liverpool and other RD50 institutes.

received in Feb. 2020



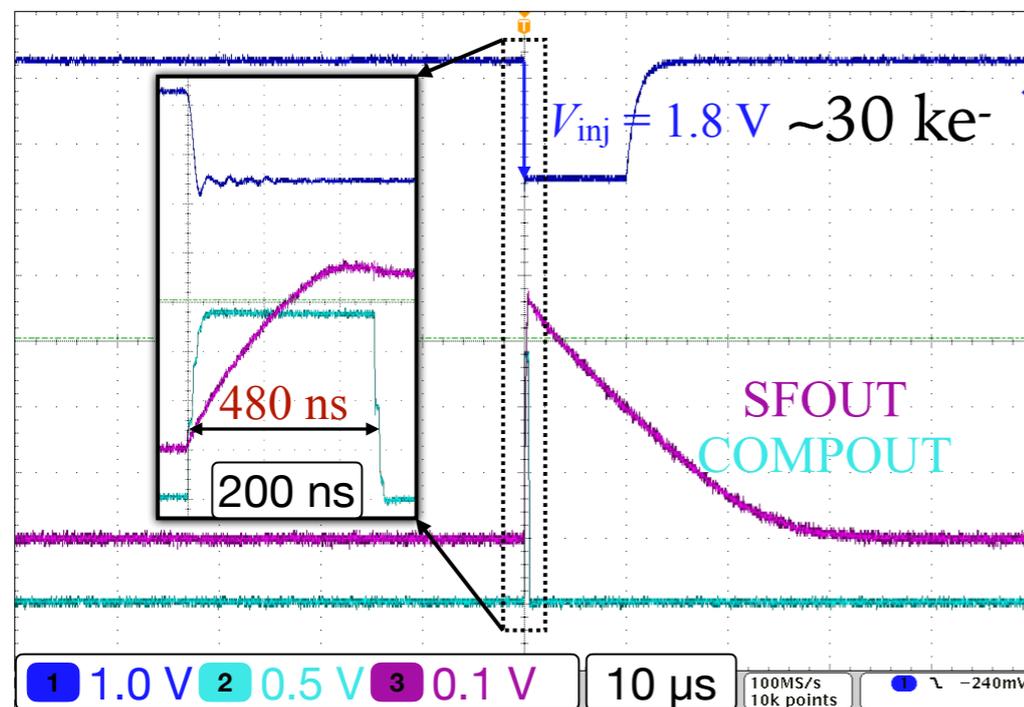
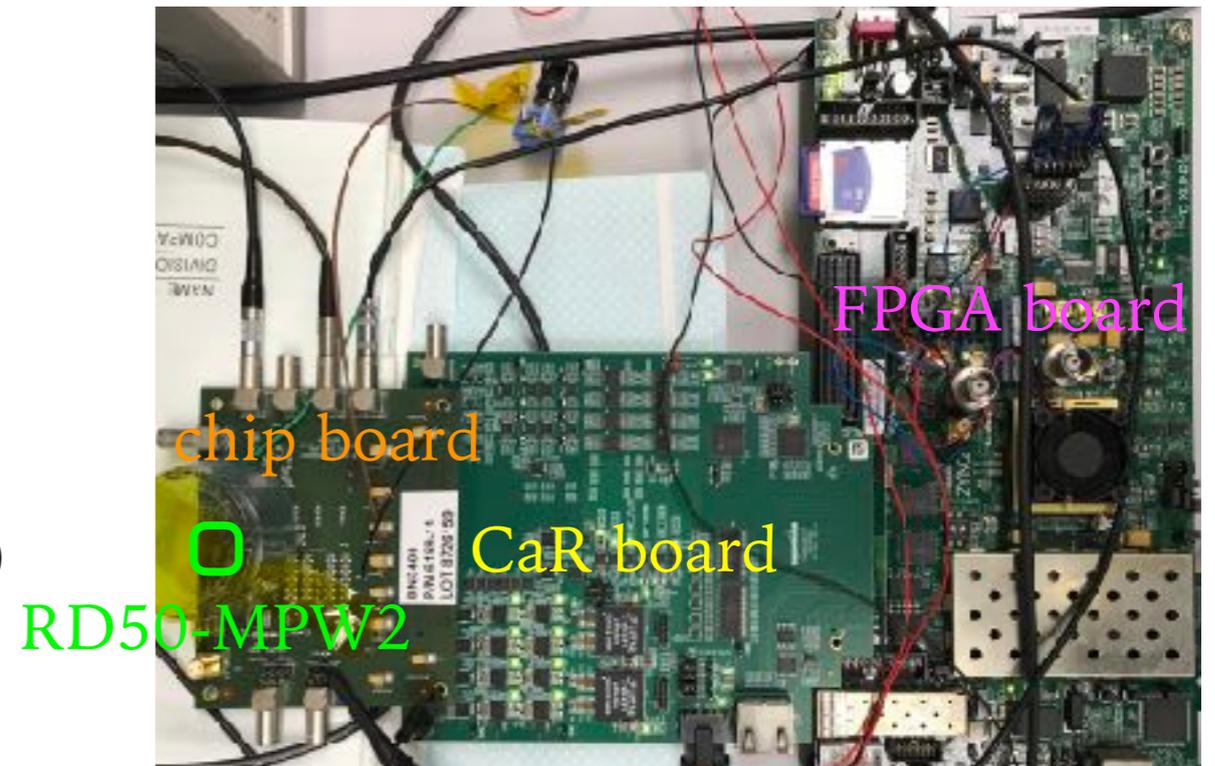
I-V of RD50-MPW1 and RD50-MPW2



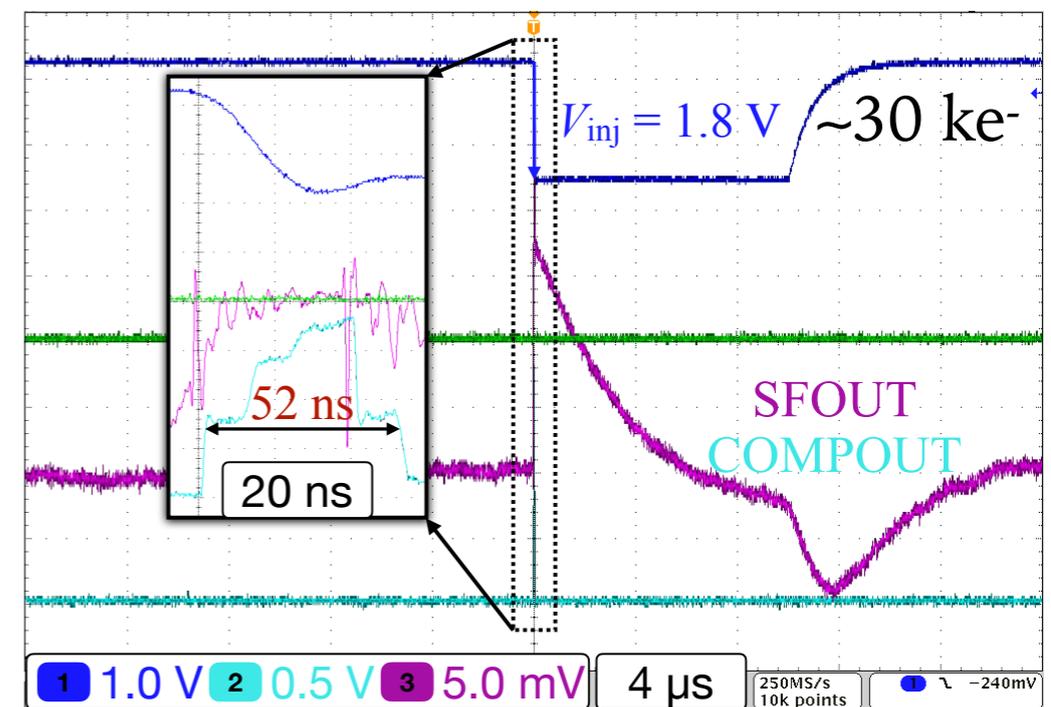
Depletion width after irradiation

RD50-MPW2 Measured Results

- DAQ system to evaluate performance of readout electronics.
 - developed within CERN-RD50
- Two pixel flavours with high processing speed:
 - Continuous-reset (~ 500 ns for 30 ke $^-$)
 - Switched-reset (~ 50 ns, but not ToT compatible)

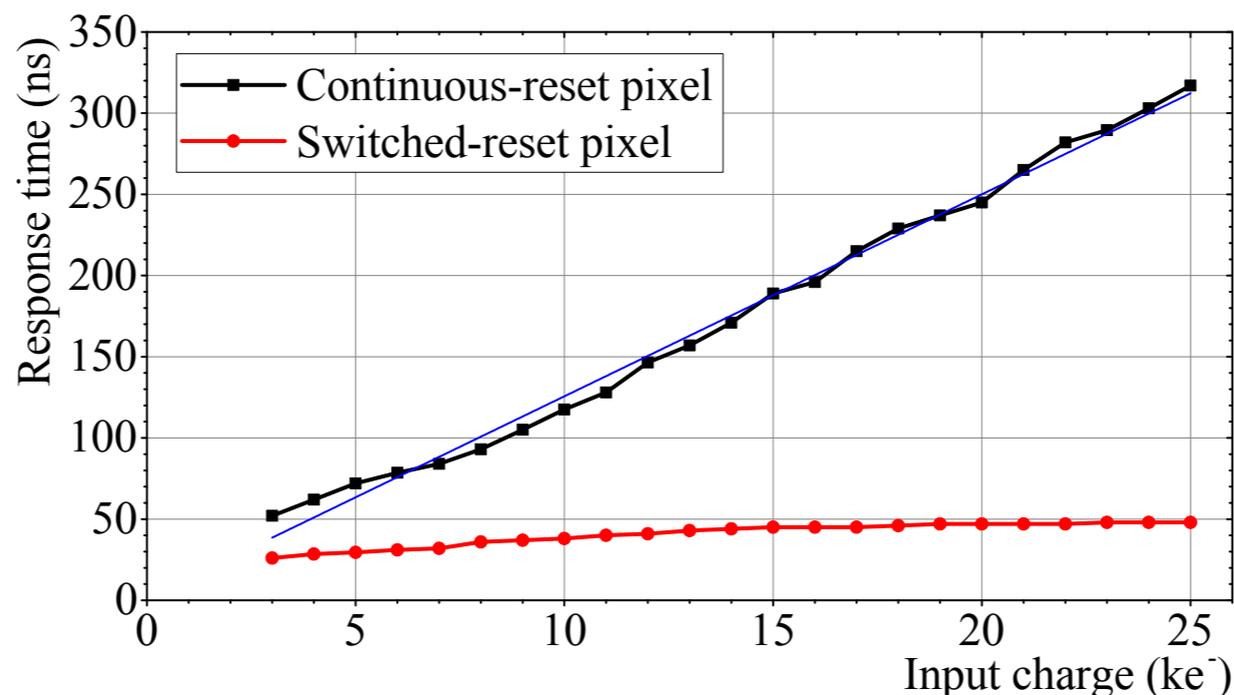


Continuous-reset pixel

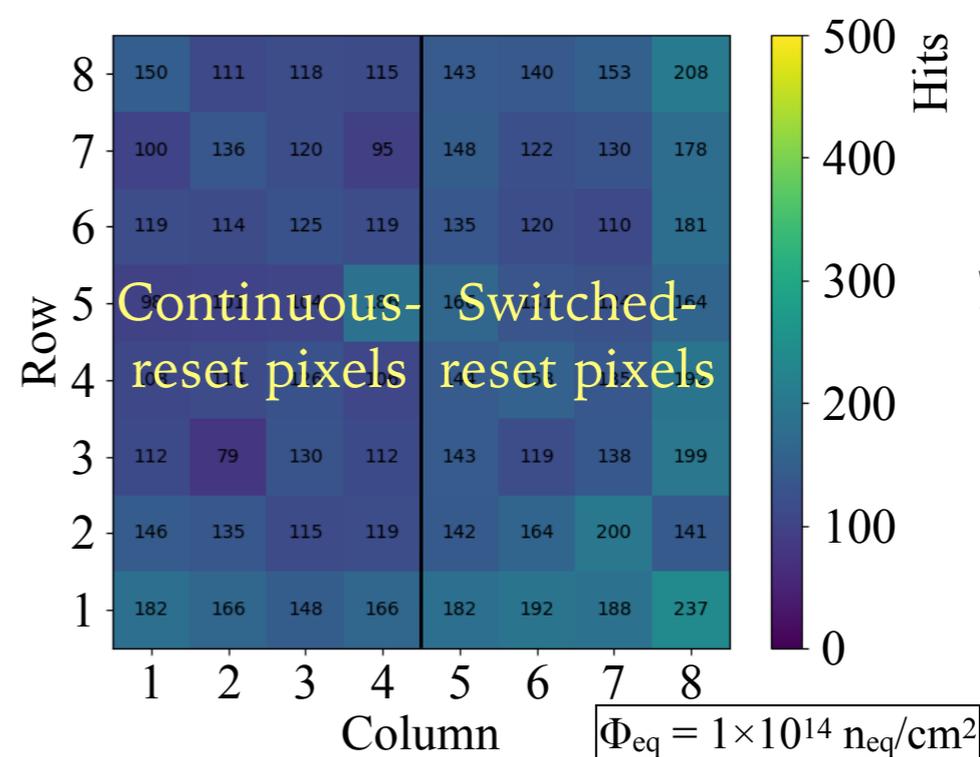
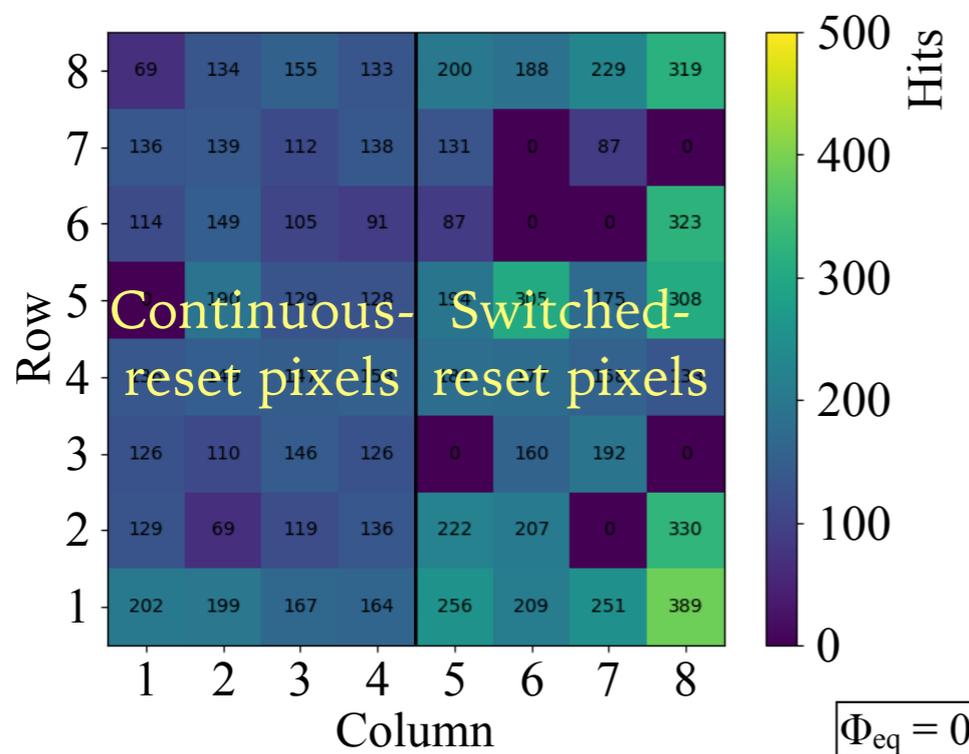


Switched-reset pixel

- Dead time for different input charge.



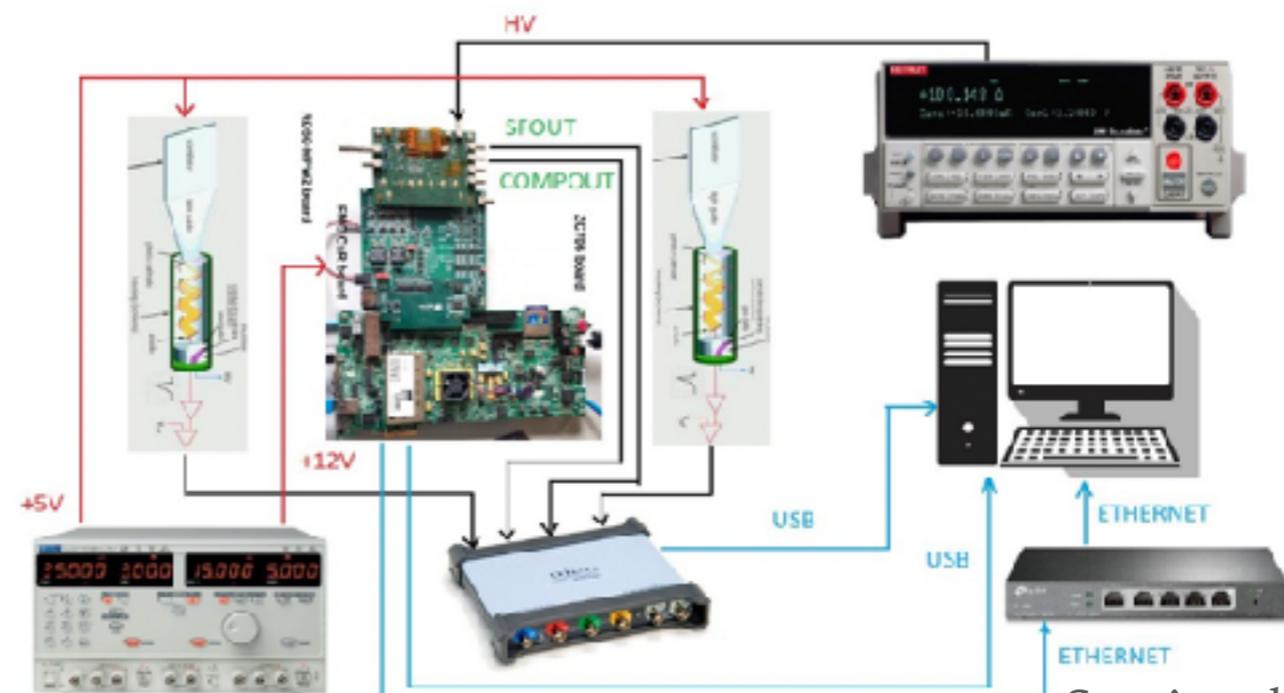
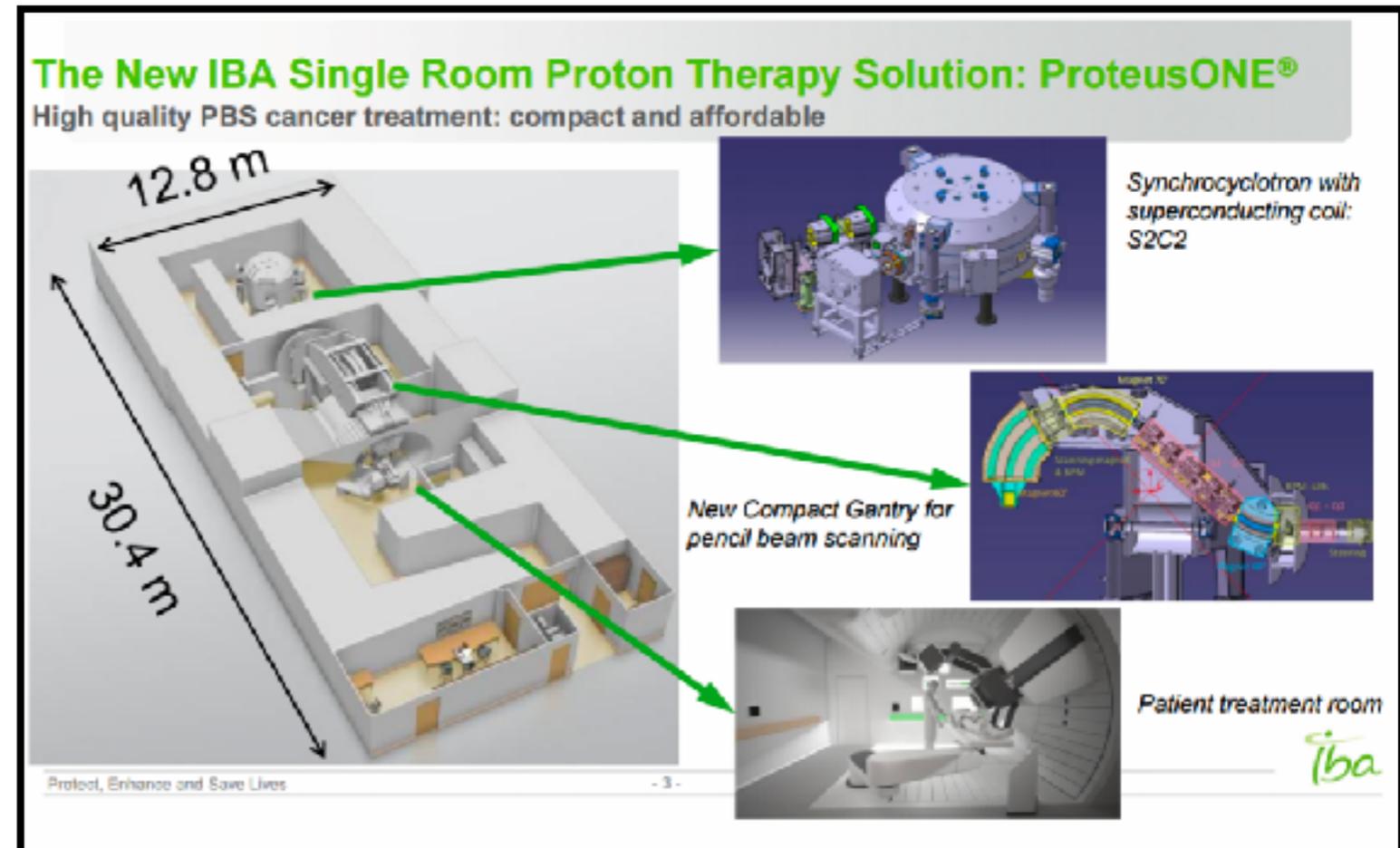
- Hit maps of pixel matrix exposed to radioactive source.



P. Sieberer 2020

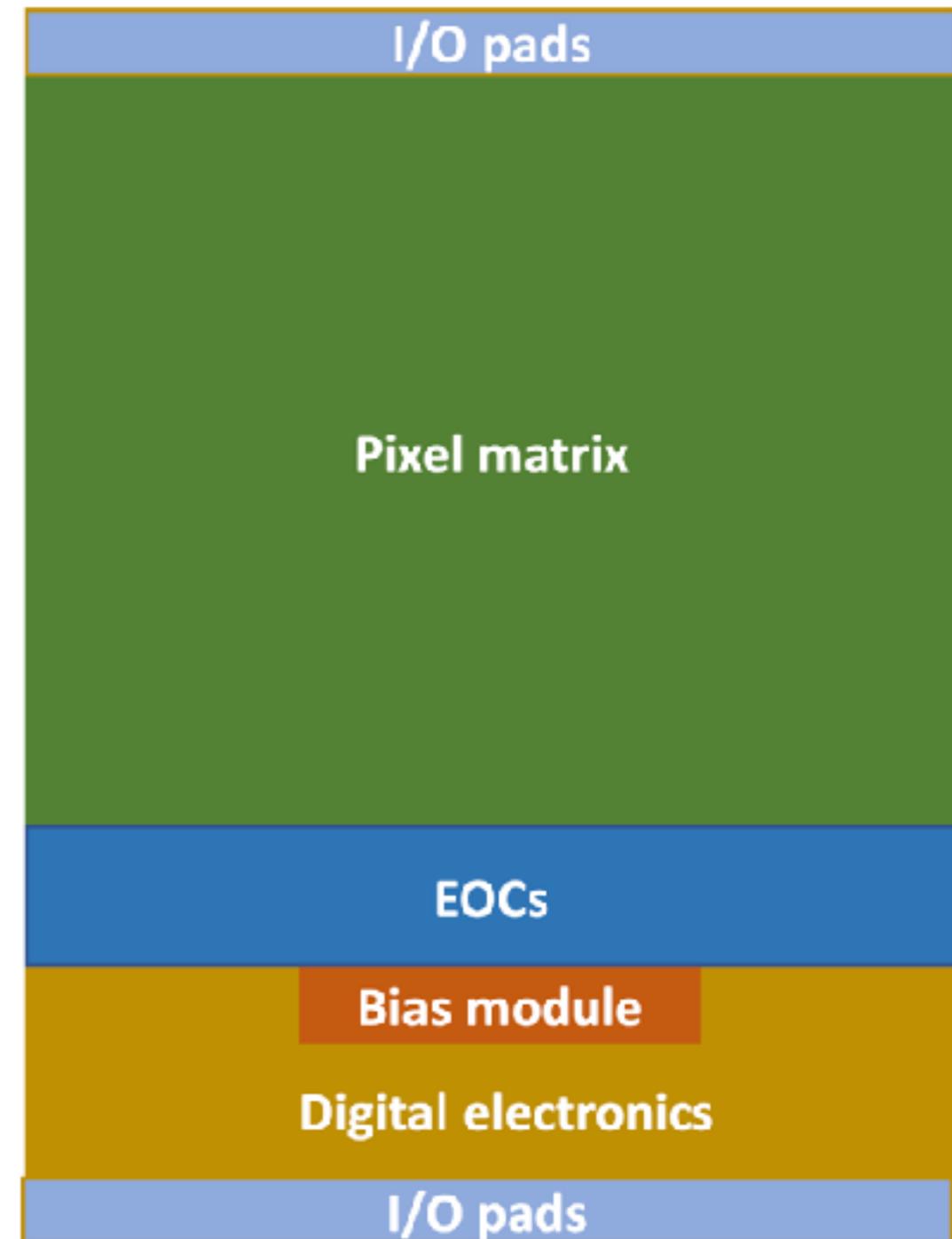
RD50-MPW2 beam test

- Beam test at Rutherford Cancer Centre in Northumberland on 10th May.
- Protons delivered in bunches with a 1 kHz rate
 - Beam energy: 70 -229 MeV
 - Min beam spot size: 3.5 mm
- First beam test by HV-CMOS group.
- DAQ setup prepared.



Sam's talk yesterday

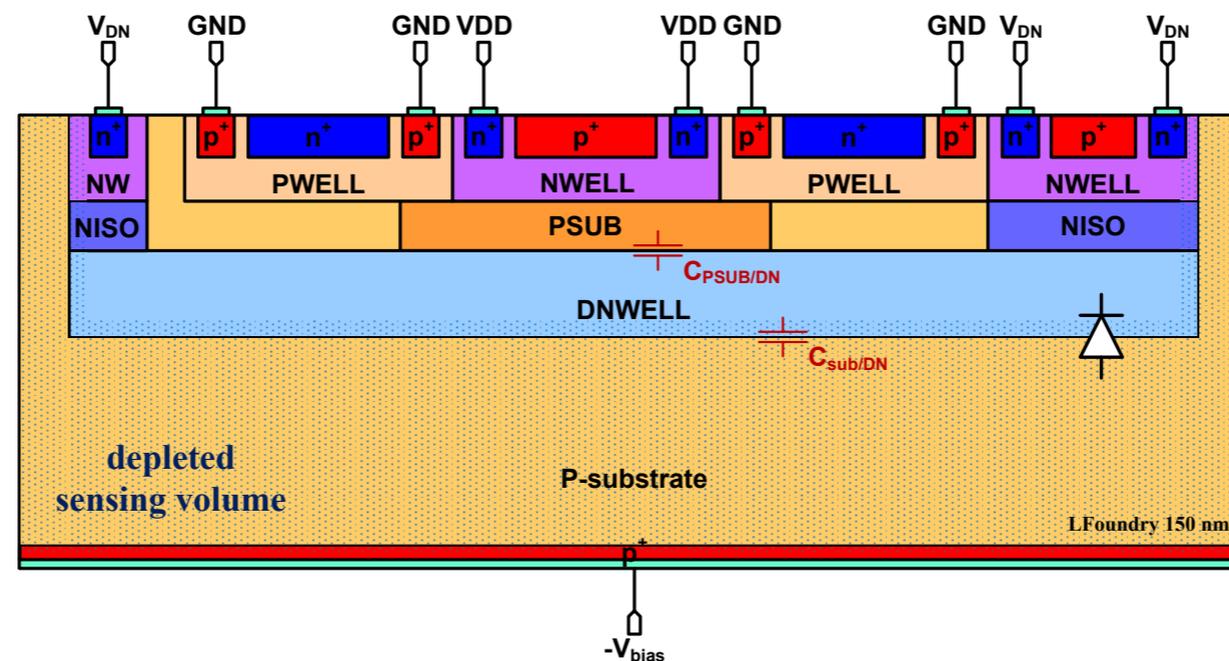
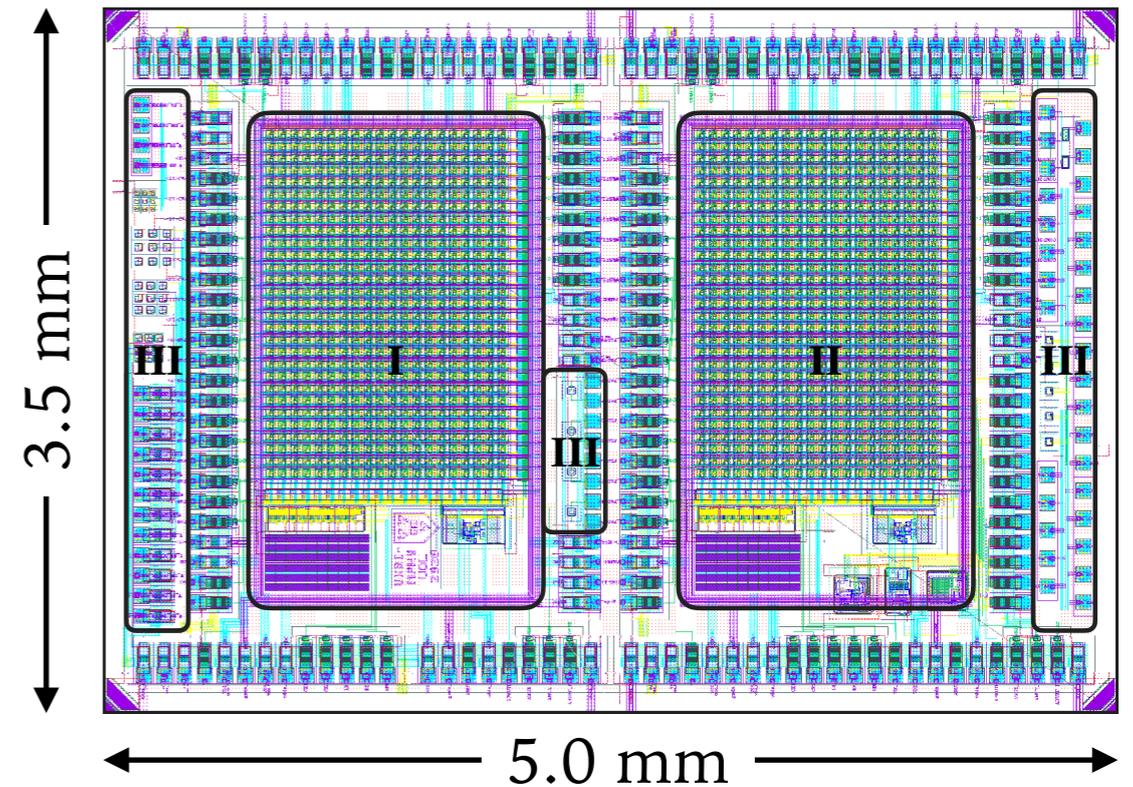
- **RD50-MPW3** is being designed within RD50.
- Incorporates the knowledge from RD50-MPW1 and RD50-MPW2.
- Contains large pixel matrix with full analog and digital readout electronics.
- Optimise peripheral readout circuitry to allow high-rate data transmission.
- Explore new amplifier flavours for improvements in timing and power.



RD50-MPW3 Floorplan
to be submitted in Oct. 2021

- **UKRI-MPWO** a Liverpool internal project.
- Design by Liverpool HV-CMOS group (WFH) during the lockdown.
- Backside biased with no topside contact
 - Higher breakdown
 - Better radiation tolerance
- 2 large pixel matrices for more statistics.

submitted in Nov. 2020



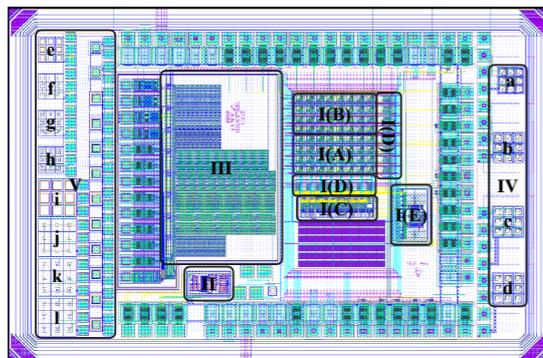
Backside biased only

- High breakdown voltage (~ 1000 V).
- Test Enclosed Layout Transistors (ELT) for better radiation tolerance.
- DAQ development in progress.
- Wafer production completed.
- Backside processing in progress now in IBS.
- Will be delivered in the following weeks.

Summary and Next step

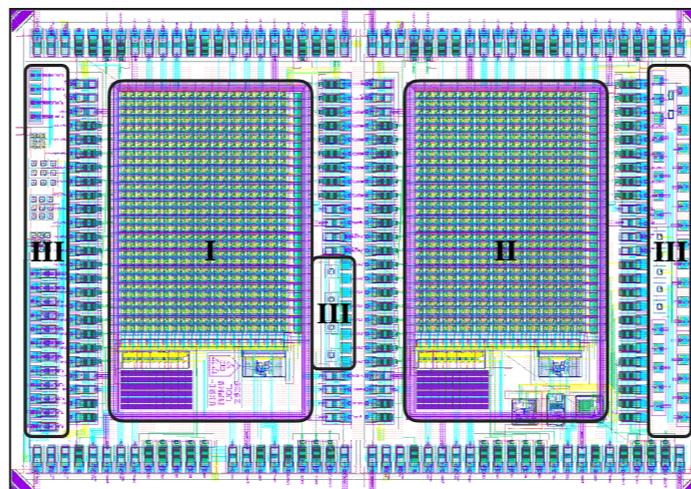
- RD50-MPW2 works well in accordance with design.
- RD50-MPW2 beam test next month.
- Receive and test UKRI-MPW0 in the near weeks.
- Submit RD50-MPW3 in October.

received in Feb. 2020



RD50-MPW2

submitted in Nov. 2020



UKRI-MPW0

to be submitted
in Oct. 2021



RD50-MPW3